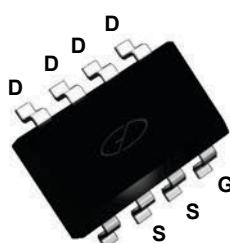
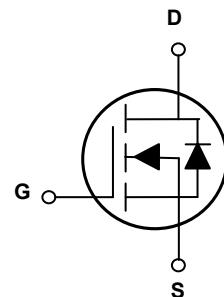


Main Product Characteristics

$V_{(BR)DSS}$	40V
$R_{DS(ON)}$	19mΩ
I_D	6.7A



SOP-8



Schematic Diagram

Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



Description

The GSFQ4910 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supply and a wide variety of other applications.

Absolute Maximum Ratings ($T_C=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	40	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current – Continuous ($T_A=25^\circ\text{C}$)	I_D	6.7	A
Drain Current – Continuous ($T_A=70^\circ\text{C}$)		5.4	A
Drain Current – Pulsed ¹	I_{DM}	26.8	A
Power Dissipation ($T_A=25^\circ\text{C}$)	P_D	1.47	W
Power Dissipation – Derate above 25°C		0.12	W/°C
Storage Temperature Range	T_{STG}	-55 to +150	°C
Operating Junction Temperature Range	T_J	-55 to +150	°C

Thermal Characteristics

Parameter	Symbol	Typ.	Max.	Unit
Thermal Resistance Junction to Ambient	$R_{\theta JA}$	---	85	°C/W

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	40	---	---	V
$\Delta \text{BV}_{\text{DSS}}$ Temperature Coefficient	$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	Reference to 25°C , $I_{\text{D}}=1\text{mA}$	---	0.034	---	$\text{V}/^\circ\text{C}$
Drain-Source Leakage Current	I_{DSS}	$V_{\text{DS}}=40\text{V}, V_{\text{GS}}=0\text{V}, T_J=25^\circ\text{C}$	---	---	1	μA
		$V_{\text{DS}}=32\text{V}, V_{\text{GS}}=0\text{V}, T_J=85^\circ\text{C}$	---	---	10	μA
Gate-Source Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$	---	---	± 100	nA
On Characteristics						
Static Drain-Source On-Resistance	$R_{\text{DS(ON)}}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=6\text{A}$	---	16	19	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=4\text{A}$	---	20	25	$\text{m}\Omega$
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{GS}}=V_{\text{DS}}, I_{\text{D}}=250\mu\text{A}$	1.2	1.5	2.5	V
$V_{\text{GS(th)}}$ Temperature Coefficient	$\Delta V_{\text{GS(th)}}$		---	-4.3	---	$\text{mV}/^\circ\text{C}$
Forward Transconductance	g_{fs}	$V_{\text{DS}}=10\text{V}, I_{\text{D}}=3\text{A}$	---	6	---	S
Dynamic and Switching Characteristics						
Total Gate Charge ^{2, 3}	Q_g	$V_{\text{DS}}=32\text{V}, V_{\text{GS}}=10\text{V}, I_{\text{D}}=6\text{A}$	---	11.8	23	nC
Gate-Source Charge ^{2, 3}	Q_{gs}		---	1.7	3.4	
Gate-Drain Charge ^{2, 3}	Q_{gd}		---	4	8	
Turn-On Delay Time ^{2, 3}	$T_{\text{d(on)}}$	$V_{\text{DD}}=20\text{V}, V_{\text{GS}}=10\text{V}, R_{\text{G}}=3.3\Omega, I_{\text{D}}=1\text{A}$	---	5	10	ns
Rise Time ^{2, 3}	T_r		---	8	16	
Turn-Off Delay Time ^{2, 3}	$T_{\text{d(off)}}$		---	17	34	
Fall Time ^{2, 3}	T_f		---	5	10	
Input Capacitance	C_{iss}	$V_{\text{DS}}=20\text{V}, V_{\text{GS}}=0\text{V}, F=1\text{MHz}$	---	722	1440	pF
Output Capacitance	C_{oss}		---	83	166	
Reverse Transfer Capacitance	C_{rss}		---	61	122	
Gate Resistance	R_g	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=0\text{V}, F=1\text{MHz}$	---	2.1	---	Ω
Drain-Source Diode Characteristics and Maximum Ratings						
Continuous Source Current	I_s	$V_{\text{G}}=V_{\text{D}}=0\text{V}$, Force Current	---	---	6.7	A
Pulsed Source Current	I_{SM}		---	---	13.4	A
Diode Forward Voltage	V_{SD}	$V_{\text{GS}}=0\text{V}, I_{\text{S}}=1\text{A}, T_J=25^\circ\text{C}$	---	---	1	V

Note:

1. Repetitive Rating: Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed, pulse width $\leq 300 \mu\text{s}$, duty cycle $\leq 2\%$.
3. Essentially independent of operating temperature.

Typical Electrical and Thermal Characteristic Curves

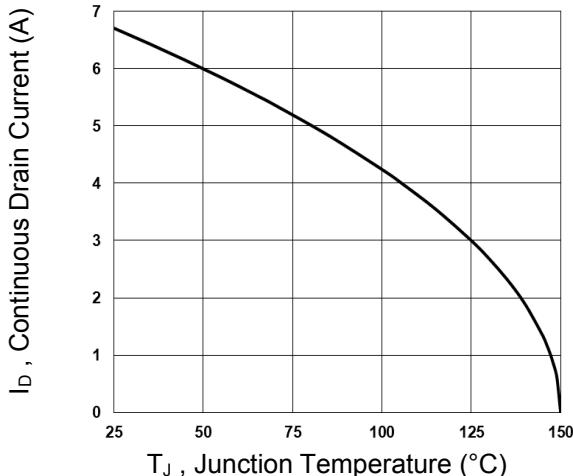


Fig.1 Continuous Drain Current vs. T_J

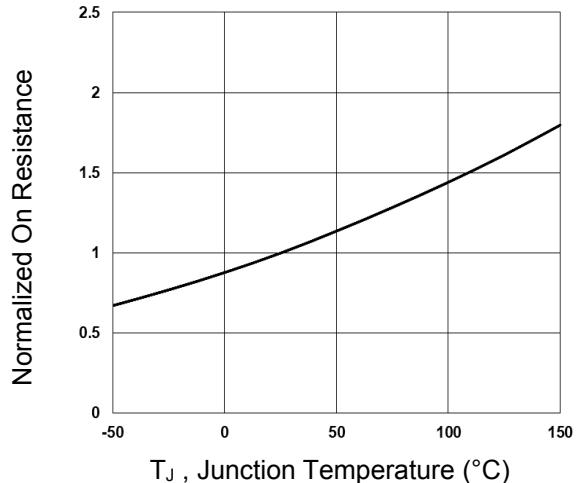


Fig.2 Normalized $R_{DS(ON)}$ vs. T_J

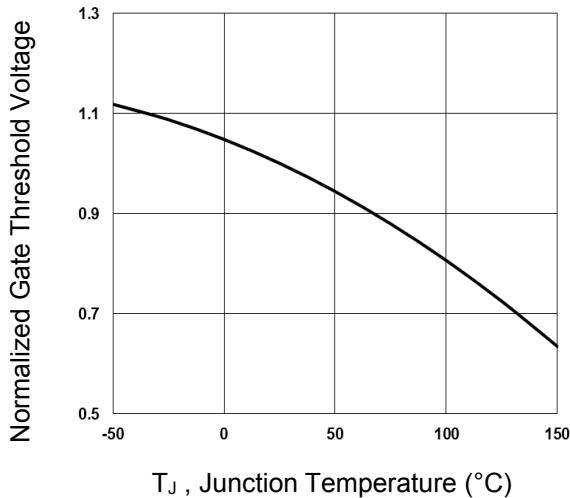


Fig.3 Normalized V_{th} vs. T_J

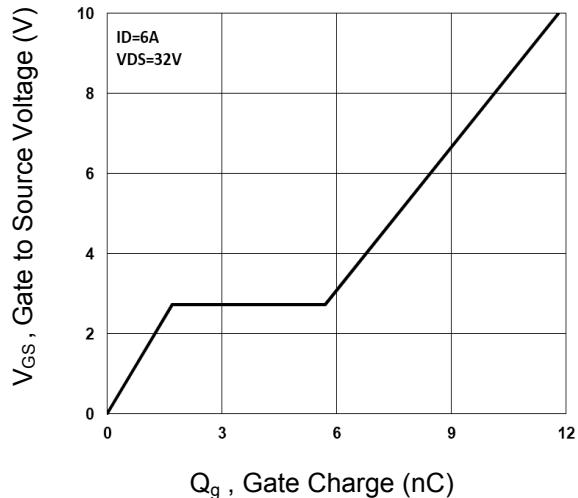


Fig.4 Gate Charge Waveform

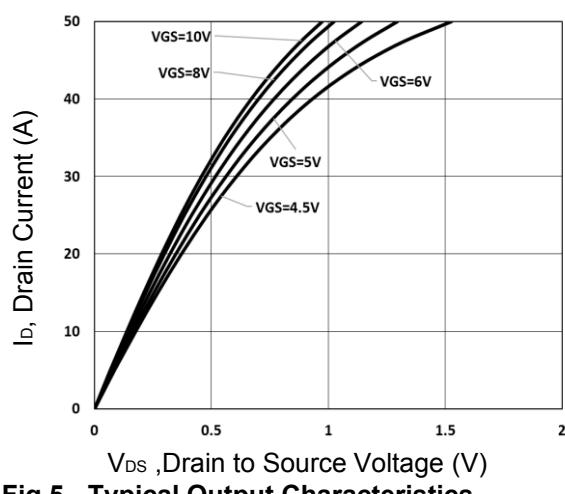


Fig.5 Typical Output Characteristics

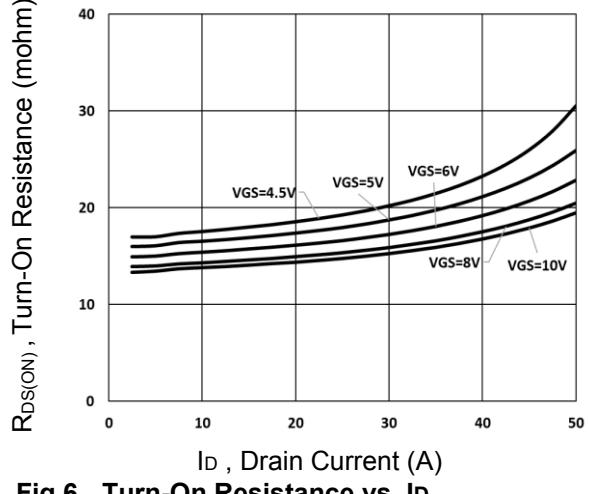
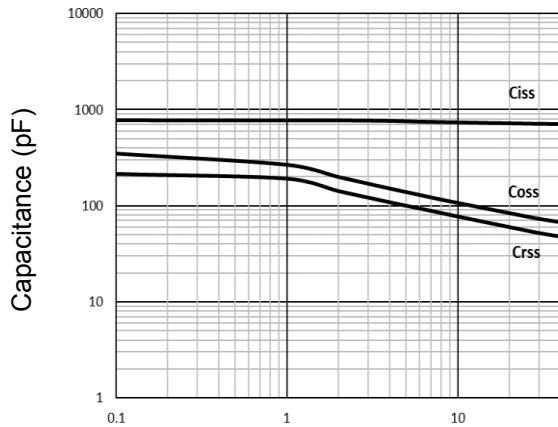
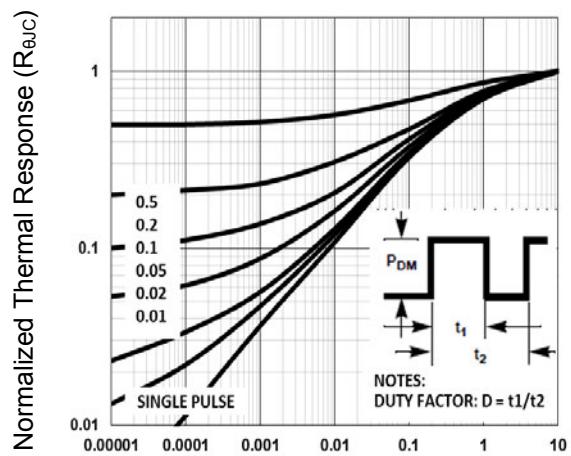


Fig.6 Turn-On Resistance vs. I_D

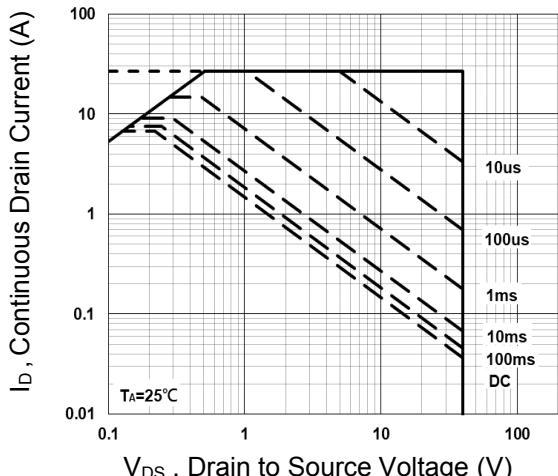
Typical Electrical and Thermal Characteristic Curves



V_{DS} , Drain to Source Voltage (V)
Fig.7 Capacitance Characteristics



Square Wave Pulse Duration (S)
Fig.8 Normalized Transient Impedance



$T_A=25^\circ\text{C}$
Fig.9 Maximum Safe Operation Area

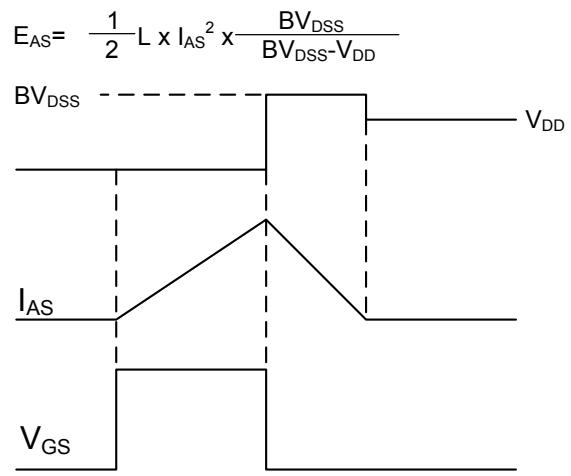


Fig.10 E_{AS} Waveform

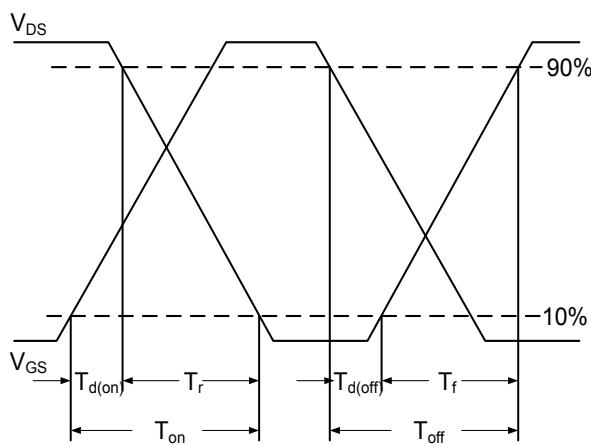
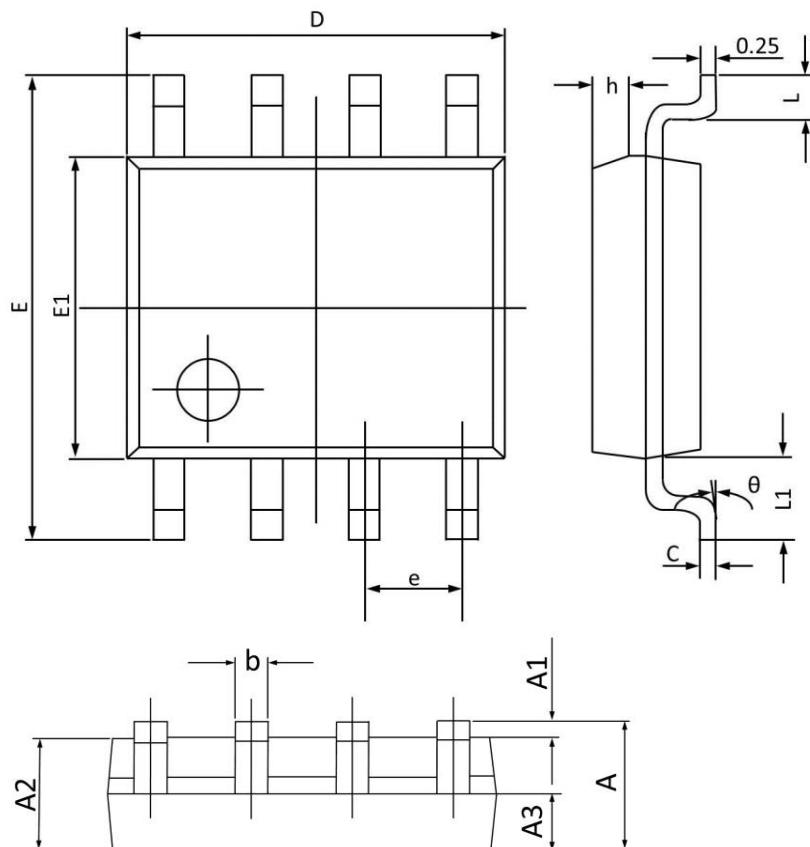


Fig.11 Switching Time Waveform

Package Outline Dimensions

SOP-8



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.068
A1	0.100	0.250	0.004	0.009
A2	1.300	1.500	0.052	0.059
A3	0.600	0.700	0.024	0.027
b	0.390	0.480	0.016	0.018
c	0.210	0.260	0.009	0.010
D	4.700	5.100	0.186	0.200
E	5.800	6.200	0.229	0.244
E1	3.700	4.100	0.146	0.161
e	1.270(BSC)		0.050(BSC)	
h	0.250	0.500	0.010	0.019
L	0.500	0.800	0.019	0.031
L1	1.050(BSC)		0.041(BSC)	
θ	0°	8°	0°	8°